

DESCRIPTION OF OPERATION

Preparation:

The operation of the Hunter Mini-Plating System is extremely simple and consists of the following basic steps:

If the surface to be plated is discolored or oxidized polish thoroughly with a fine metal polish until discoloration or oxide surface is removed. Wipe the surface well with a clean cloth after polishing.

De-Greasing:

Connect the part to be plated to the negative (-) of the D.C. supply. Connect the absorbent pen to the positive (+) of the D.C. supply. Adjust working voltage to 10-12 volts. Hold the tip of the absorbent pen so that its entire surface contacts the part and then lightly rub back and forth in a slow stroking action. Small bubbles will form to remove oil and grease. Rinse after completing degreasing action.

Plating:

Working voltage required for plating varies with the type of plating pen used. The voltage required is indicated on each pen. Adjust voltage to indicated value, connect part being plated to the negative (-) and the plating pen to the positive (+) of the supply. Apply the tip of the pen to the object so that its entire surface is in contact. Move the pen lightly back and forth and the plating will be deposited. Finally, rinse the part in water and wipe with a soft cloth.

TECHNICAL DETAILS

PLATING THICKNESS

Maximum plating thickness attainable with standard pens is 1.5 - 1.8 microns. Heavy type pens can attain 3 - 3.6 microns thickness. Typical times to achieve various thicknesses on a 1" x 1" copper surface are as follows:

Pen Type	2 Minutes	3 Minutes
Gold	0.5 microns	0.8 microns
Palladium	0.5 microns	0.8 microns
Silver	0.5 microns	0.8 microns
Rhodium	0.7 microns	1.0 microns
Nickel	0.4 microns	0.6 microns
Black-Nickel	0.5 microns	0.6 microns
Copper, Zinc, Tin & Chrome Color	0.3 microns	0.5 microns
Gold Heavy-Rapid Type	0.8 microns	1.2 microns
Silver Heavy-Rapid Type	0.8 microns	1.2 microns
Copper Heavy-Rapid Type	0.6 microns	1.0 microns
Nickel Heavy-Rapid Type	0.8 microns	1.2 microns

PLATING COVERAGE

Each pen contains 10 ml. of concentrated plating solution and will plate approximately 300 sq. inches of surface.

Partial List of Users of Hunter Mini-Plating System

Cincinnati Milacron	E.I. DuPont de Nemour	IBM Corporation
Hewlett Packard	Hughes Aircraft	Raytheon
AT&T	R-Tec	U.S. Air Force
The Aerospace Corporation	Texas Instruments	Motorola Inc.
U.S. Army	U.S. Navy	TRW Technar
Martin Marietta	General Motors/Fisher Division	Westell Inc.
K & L Microwave Inc.	Medicomp Inc.	Powerex Inc.
Electro Etch Circuits	Charleston Naval Shipyard	Princeton University
New England Sciences	Harvard University	Aritech
Vectron Laboratories Inc.	NASA Lewis Research Center	Zenith
Argonne National Laboratories	Pacific Gas & Electric Company	King Radio/Bendix
Control Data Corporation	Optek Technology Inc.	Bell Laboratories
Burton Electrical Engineering	National Instruments	G E Company
Leeds & Northrup	Matrox Electronics Systems	Teradyne
Florida Steel Corporation	Miltope Corporation	

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